



**PATENT**

**THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of:  
Yian-Liang Kuo

Confirmation Number: 9795

Serial No.: 10/718,192

Group Art Unit: 2815  
Examiner: Chu, Chris

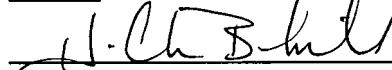
Filed: 11/20/2003

TKHR Docket No. 252016-1720  
Top-Team Ref. 0503-30125US

For: **A HEAT SPREADER BALL GRID ARRAY (HSBGA) DESIGN FOR LOW-K  
INTEGRATED CIRCUITS (IC)**

**Certificate of Mailing**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment; Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 21, 2004.

  
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Signature – Hui Chin Barnhill

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Mail Stop Amendment  
Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The non-final Office Action mailed September 22, 2004 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks. In this regard, **Amendments to the Specification** begin on page 2; **Amendments to the Claims** begin on page 6, and **Remarks** begin on page 13 of this paper.